


StackName: Rigid 1	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/6	
Date: 27/05/2011	Associated Documents:						
Author: Richard Attrill							
Department: Engineering							
Site:							

Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
1		Photoimageable Solder Mask			17.780		4.000	0.0000	
2		FR4 Core	Signal	48.250	48.250				
			Plane	125.000	125.000	50.000	4.200	0.0195	
		PrePreg 1080		18.000	18.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		Coverlay		50.000	50.000		3.500	0.0195	
3			Signal	18.000	18.000				
4		Flex Core	Plane	50.000	50.000	0.000	4.200	0.0195	
			Plane	18.000	18.000				
		Coverlay		50.000	50.000		3.500	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
5			Plane	18.000	18.000				
6		FR4 Core	Signal	125.000	125.000	50.000	4.200	0.0195	
			Signal	48.250	48.250				
		Photoimageable Solder Mask			17.780		4.000	0.0000	

Copper Thickness = 168.500 | Dielectric Thickness = 662.680 | Solder Mask Thickness = 35.560 | Stack Up Thickness = 831.180 | Stack Up Thickness with Soldermask = 866.740  
 Stack Up Cost = 21.50

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	1	2	2	Laser PTH
	1	6	1	Mechanical PTH
	6	5	2	Laser PTH

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	4	1.00	4.00	4	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00
							13.00		13.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 13.00 |

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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
3		Coverlay		50.000	50.000		3.500	0.0195	
		Signal		18.000	18.000				
4		Flex Core		50.000	50.000	0.000	4.200	0.0195	
		Plane		18.000	18.000				
		Coverlay		50.000	50.000		3.500	0.0195	

Copper Thickness = 36.000 | Dielectric Thickness = 150.000 | Solder Mask Thickness = 0.000 | Stack Up Thickness = 186.000 | Stack Up Thickness with Soldermask = 186.000  
Stack Up Cost = 4.00

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	3	4	1	Mechanical PTH

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost	
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00	
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00	
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	4	1.00	4.00	4	4.00	
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00	
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00	
							13.00	13.00		

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 13.00 |  
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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
1		Photoimageable Solder Mask			17.780		4.000	0.0000	
2		FR4 Core	Signal	48.250	48.250				
			Plane	125.000	125.000	50.000	4.200	0.0195	
3		PrePreg 1080		18.000	18.000				
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		Coverlay		50.000	50.000		3.500	0.0195	
4		Flex Core	Signal	18.000	18.000				
			Plane	50.000	50.000	0.000	4.200	0.0195	
5		Coverlay		18.000	18.000				
		Coverlay		50.000	50.000		3.500	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
6		FR4 Core	Plane	18.000	18.000				
			Signal	125.000	125.000	50.000	4.200	0.0195	
6		Photoimageable Solder Mask			17.780		4.000	0.0000	

Copper Thickness = 168.500 | Dielectric Thickness = 662.680 | Solder Mask Thickness = 35.560 | Stack Up Thickness = 831.180 | Stack Up Thickness with Soldermask = 866.740  
 Stack Up Cost = 21.50

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	1	2	2	Laser PTH
	1	6	1	Mechanical PTH
	6	5	2	Laser PTH

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	4	1.00	4.00	4	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00
							13.00		13.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 13.00 |

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